# EMBEDDED PROCESSING ANALOG & CONNECTIVITY



JUNE 26, 2025 DAVIN LEE SVP AND GM OF ANALOG & CONNECTIVITY AND EMBEDDED PROCESSING RENESAS ELECTRONICS CORPORATION



### AT A GLANCE EMBEDDED PROCESSING

#### Our products / technologies



32bit Arm Cortex-M based MCU for intelligent IoT



32bit high-performance, high-efficiency MCU



16bit low power consumption MCU



64bit MPU for HMI, e-AI, real-time control & industrial networking



2024 Revenue



### **GROWTH DRIVERS** EMBEDDED PROCESSING



#### © 2025 Renesas Electronics Corporation. All rights reserved.

# **EMBEDDED PROCESSING STRATEGY**



#### © 2025 Renesas Electronics Corporation. All rights reserved.

## SCALABLE EMBEDDED PROCESSING PLATFORM



Streamlined Software, Development Tools and Solutions for easy migration Common IPs & Compute Cores used across MCU and MPU families

FSP: Flexible Software Package

## **MCU SHARE GROWTH**



Graphs created by Renesas based on Gartner Research. Calculations performed by Renesas Source: Gartner®, Market Share: Semiconductors by End Market, Worldwide, 2024, Rajeev Rajput et al., 2 April 2025, MCU for Industrial & IoT = Total Microcontroller excluded Automotive application GARTNER is a registered trademark and service mark of Gartner, Inc. and/or its affiliates in the U.S. and internationally and is used herein with permission. All rights reserved. Gartner does not endorse any vendor, product or service depicted in its research publications, and does not advise technology users to select only those vendors with the highest ratings or other designation. Gartner research publications consist of the opinions of Gartner's research organization and should not be construed as statements of fact. Gartner disclaims all warranties, expressed or implied, with respect to this research, including any warranties of merchantability or fitness for a particular purpose.



# **PHASE 1: ACCELERATING GROWTH IN CHINA & INDIA**



## **LEVERAGING CORE TECHNOLOGIES – MOTOR CONTROL**



QE: Quick and Effective tool solution

## RENESAS REALITY AI PLATFORM HIGHLY EFFICIENT AI FOR ANY EDGE APPLICATION



Leading developer platform powering edge AI in industrial IoT & automotive applications

Auto machine learning model development

Explainable AI + hardware analytics

Ultra-low power inferences

## **Seamless developer experience**

Bridging together AI and embedded domains



## **REALITY AI - DIVERSE MARKET SUCCESS**



# Remote livestock management & virtual fencing





**Hisense** | HITACHI

#### Pump health monitoring

#### Adaptive energy efficient HVAC systems

- Ultra-low power for extended battery life (Solar powered wearable)
- High precision behavior monitoring across entire herds
- BOM reduction (sensor components optimization)

- Prevent costly equipment failure before they occur
- Reduce maintenance costs through precise fault detection in cost-effective hardware
- Improve equipment reliability & uptime

- Smart climate control, automatically fine tunes indoor conditions for comfort
- Remarkable energy efficiency and reduced carbon footprint
- Extended system life through optimized operation



## **PHASE 2: ENABLEMENT WITH DIGITALIZATION**



#### RENESAS

#### © 2025 Renesas Electronics Corporation. All rights reserved.

### **AT A GLANCE ANALOG & CONNECTIVITY**



### **GROWTH DRIVERS** ANALOG & CONNECTIVITY



Note: MRDIMM (Multiplexed Rank DIMM): Highest performance and lowest latency main memory to accelerate data center workloads

### **VERTICAL STRATEGY** INCREASING HIGH VALUE ANALOG CONTENT IN CLOUD AND DATACENTER SERVER MARKET GROWTH



\*1 System: Ultra-high throughput of 102.4 Tbps for next-gen data center and AI networking GPAK: GreenPAK Programmable Logic.

## VERTICAL STRATEGY - MEMORY INTERFACE MARKET GROWTH AND DDR5 TRANSITION AS AN OPPORTUNITY



- Complete DDR5 chipset with PMIC, TS, SPD Hub, RCD, DB
- DDR5 adoption to reach 90% in 2025
  - Gen3 ramp begins 2H 2025
  - Multi-gen support sustains ASPs
  - AI server growth drives DDR5 demand for higher bandwidth
  - Technical leadership in Gen4 and Gen5
- MRDIMMs to boost chipset content
  - Adoption accelerates in 2025
  - Positioned to lead with 6400 MT/s
  - Leader in Gen1 and Gen2 MRDIMMs

DDR6 expected by 2031; DDR5 MRDIMMs bridge the gap

\*1: Source: Renesas estimates based on Industry reports and Partner information \*2: FX \$1 = 100yen, €1 = 120yen TS: Temperature Sensor SPD: Serial Presence Detect RCD: Register Clock Driver DB: Data Buffer



### HORIZONTAL STRATEGY SCALABLE PORTFOLIO AS BEDROCK OF EDGE-CENTRIC PLATFORMS



SLAM: Simultaneous Localization And Mapping HMI: Human Machine Interface e-SKIN: Electronic Skin IPS: Inductive Position Sensing HOD/Impedance Sensing: Hands On Detection



## **SUMMARY**



Grow MCU share in 2-Phase approach

- Focus on growth regions and markets
- Renesas 365 & core technologies keys to mass market

Total solution set built on our high-value analog strengths and leading MCU portfolio

Continued infrastructure investments leading to DDR5 / MCR & timing growth along with content increases

High performance analog, sensors & connectivity products ideally suited to address market demands as edge expands





